

# SPECIFICATION

2G/3G/4G LTE Chip Antenna



Model No.: UCCL02



# 1. General Description

## 1.1 Electrical Properties

Parameter	Description				
Frequency Band	698~960/1710~2690 MHz				
Nominal Impedance	50 Ω				
Polarization	Linear				
V.S.W.R	<3.5:1				
(MHz)	698~798	824~960	1710~2170	2300~2400	2490~2690
Efficiency	54 %	58 %	55 %	75 %	65 %
Peak Gain	1.3 dBi	1 dBi	2.6 dBi	4.4 dBi	4.2 dBi
※With 37 x 118.5 mm Evaluation Board & 37 x 11.4 mm Clearance Area					

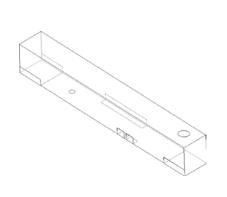
## 1.2 Mechanical Properties

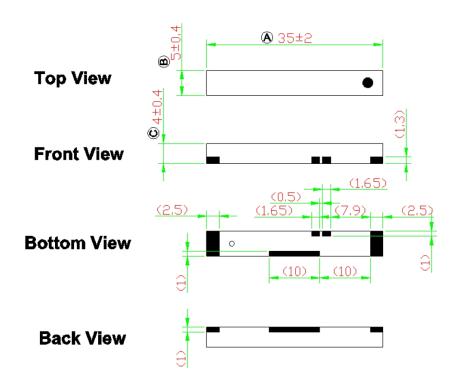
Parameter	Description	
Dimension	35×5×4 mm	
Operating Temperature	-40°C~85°C	
Storage Temperature (With Packing Sealed)	-5°C~40°C	

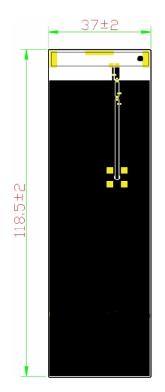


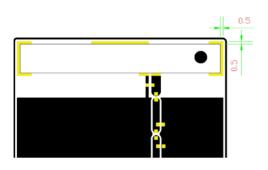
## 2. Appearance

## 2.1 Dimensions Of Antenna And Evaluation Board (Unit: mm)











#### 2.2 PIN Definitions



**Bottom View** 

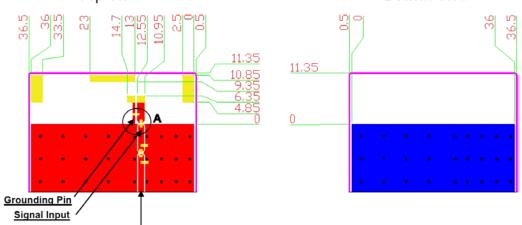
Item	PIN 1	PIN 2	PIN 3~5
Soldering Pad	Soldering Pad Tuning / Ground		N/C

#### 3. Layout Guide (Unit: mm)

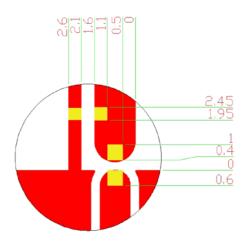
The solder land pattern (yellow marking areas) is shown as below.

Recommendation on matching circuit will be provided according to customer's installation conditions.

 $\begin{tabular}{lll} With 37 x 118.5 mm Evaluation Board \\ Top View & Bottom View \\ \end{tabular}$ 

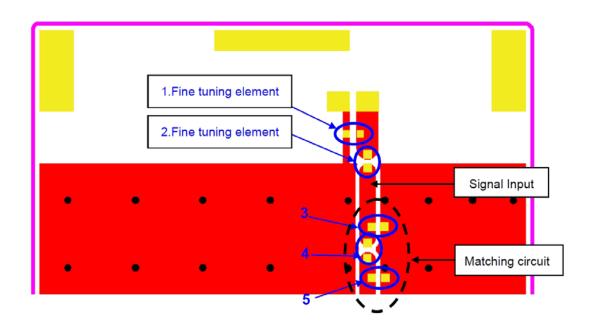


Transmission Line with 50Ω Impedance Characteristic

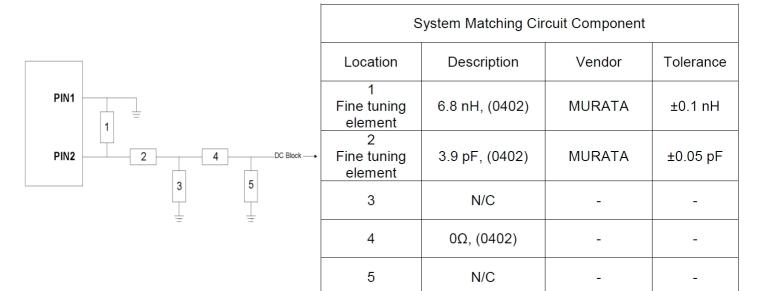




### 4. Frequency Tuning And Matching Circuit



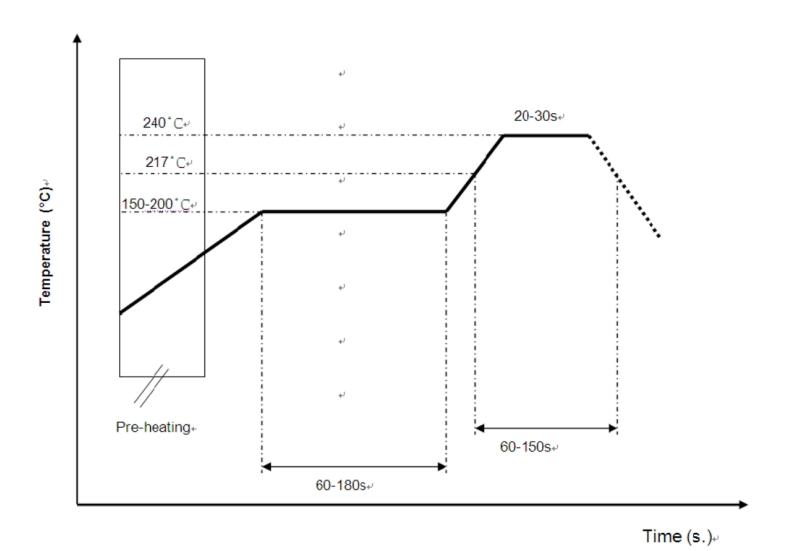
With the following recommended values of matching and tuning components, the covering frequency bands will be about  $698\sim960 \& 1710\sim2690 \text{ MHz}$  at our standard 37x118.5 mm evaluation board.



\*These are typical reference values which may need to be changed when circuit boards or part vendors are different.



## 5. Soldering Conditions

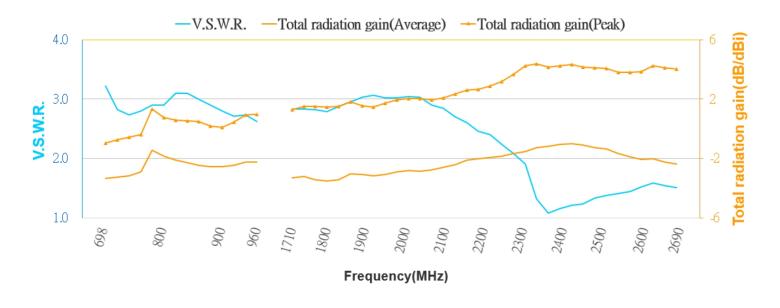


 $\label{eq:sacommended} \mbox{\@scale=1.04\eng} Recommended solder paste alloy: SAC305(Sn96.5/Ag3/Cu0.5) Lead free solder paste.$ 



#### 6. Performance

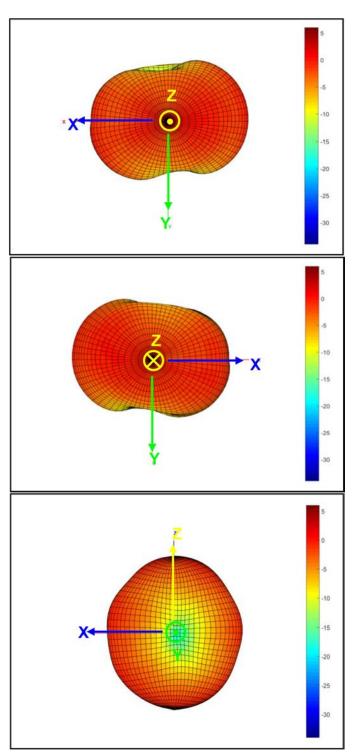
### 6.1 V.S.W.R., Average Gain, Peak Gain

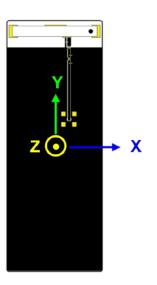




#### 6.23D Radiation Pattern

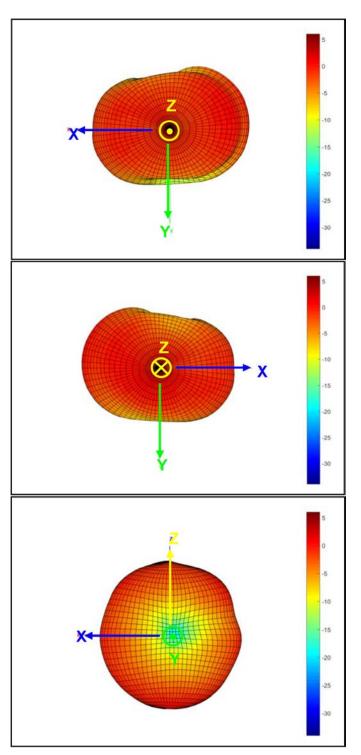
**698~798 MHz** 3D Gain Pattern @ 748 MHz (Unit : dBi)

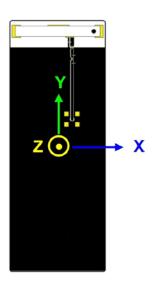






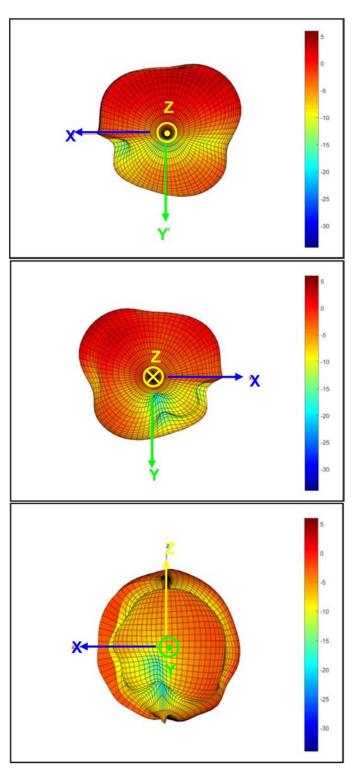
**824~960 MHz** 3D Gain Pattern @ 890 MHz (Unit : dBi)

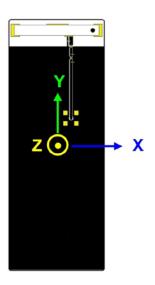






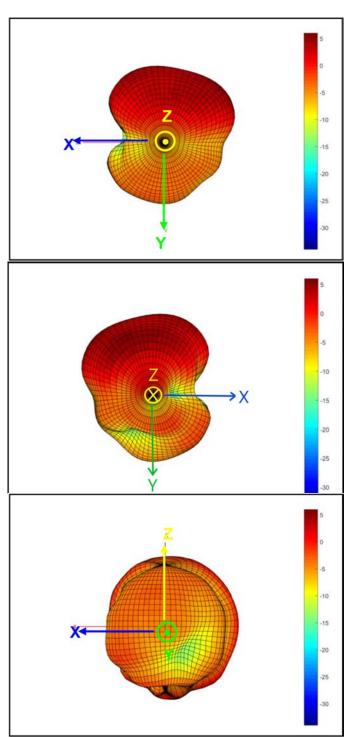
**1710~2170 MHz** 3D Gain Pattern @ 1950 MHz (Unit : dBi)

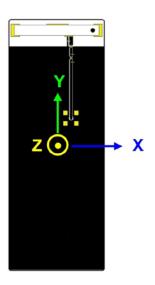






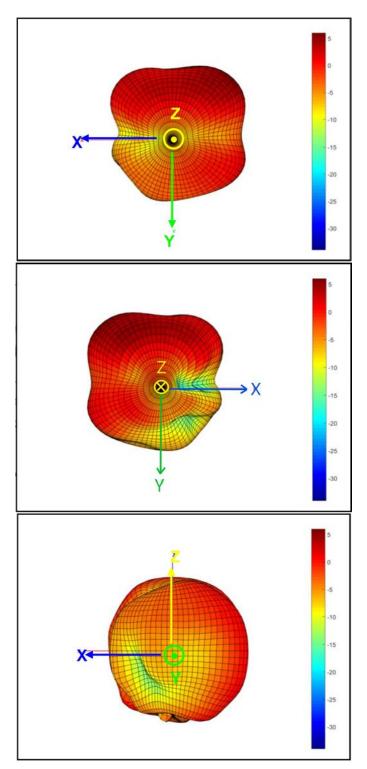
**2300~2400 MHz** 3D Gain Pattern @ 2350 MHz (Unit : dBi)

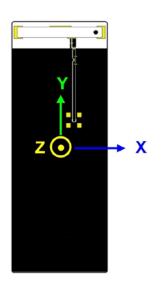






**2490~2690 MHz** 3D Gain Pattern @ 2590 MHz (Unit : dBi)

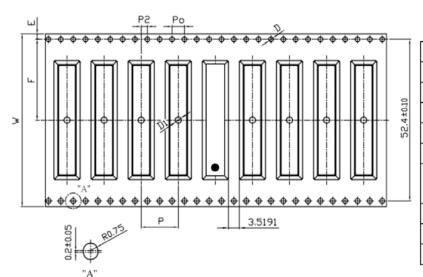






## 7. Packing

#### • Tape:



Feature	Specifications	Tolerances	
W	56.00	±0.30	
Р	12.00	±0.10	
E	1.75	±0.10	
F	26.20	±0.15	
P2	2.00	±0.15	
D	1.50	+0.10	
	1.50	-0.00	
D1	2.00	±0.10	
Po	4.00	±0.10	
10Po 40.00		±0.20	

• Reel: 1,000 pcs

